

1.0 SCOPE

This specification covers the performance requirements and test methods for the following products listed by series numbers:

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* 17	1740	IMP	EL 6 P	air Ortho Direct RAM Sig	nal Module	
17		IIVIP	LL U P		iane Signal Mouule	
"1/ * 17	1000 1403		EL 6 P	air Ortho Daughtercard &	Signal Wodule	
* 17	1495	IMP	EL 6 P	air Ortho Backplane Sigr	nal Module	
* 17	1753	IMP	EL 6 P	air Custom Backplane S	ignal Module – 3mn	n Pitch
* 17	1760	IMP	EL 6 P	air Daughtercard Signal	Module – 3mm Pitc	h
* 17	1755		EI 6 D	air Backnlane Signal Mo	dule - 3mm Pitch	
* 17	2130	IMP	PEL 6 P	air Right Angle Male (RA	M) Signal Module	
* 17	1393	IMP	PEL 6 P	air Custom Backplane S	ignal Module	
* 17	1400	IMP	EL 6 P	air Daughtercard Signal	Module	
* 17	1395	IMPEL 6 Pair Backplane Signal Module				
* 17	2003	IMPEL 5 Pair Custom Backplane Signal Module				
* 17	2010	IMPEL 5 Pair Daughtercard Signal Module				
* 17	2005	IMPEL 5 Pair Backplane Signal Module				
* 17	2135	IMP	EL 4 P	air Right Angle Male (RA	M) Signal Module -	- 3mm Pitch
* 17	1329	IIVIP IMP	EL4P FI4P	air Daugniercaru Signal air Custom Rackolane S	iniodule – Smin Pitc ignal Module – Smr	n Pitch
* 17	1325	IMP	PEL 4 P	air Backplane Signal Mo	dule – 3mm Pitch	h
				· • · · · · · · · · ·		
* 17	2140	IMP	PEL 4 P	air Right Angle Male (RA	M) Signal Module	
* 17	1313	IMP	EL 4 P	air Custom Backplane S	ignal Module	
^ 1/ * 17	1315 1320	IMP IMP	EL4P	air Backplane Signal Mo air Daughtercard Signal	aule Module	
* 47	1215			air Backplana Signal Ma	dulo	
* 17	1333	IMP	PEL 3 P	air Custom Backplane S	ignal Module	
* 17	1990	IMP	PEL 3 P	air Daughtercard Signal	Module	
* 17	1335	IMP	EL 3 P	air Backplane Signal Mo	dule	
17.	2390		CLZF		Aivi) Signal Module	
* 17	1/43		יידע EL 2 P	air Custom Backplane S	Ignal Module	
* 17	1750	IMP	EL 2 P	air Daughtercard Signal	Module	
* 17	1745	IMP	PEL 2 P	air Backplane Signal Mo	dule	

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PRODUCT SPECIFICATION

The IMPEL interconnect system consists of modular groupings of differential signals with optional integrated guidance. These connectors are two-piece devices, which connect two printed circuit boards. The right angle receptacle connectors (daughtercard) and header pin connectors (backplane) are through-hole devices with eye-of-the-needle compliant pin terminals.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME

IMPEL

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

Refer to the appropriate sales drawings for information on dimensions, materials, platings, and markings. The backplane header pins and shields are lubricated in the contact area with an approved lubricant per industry standard Telcordia GR-1217-CORE, Section 5.3.

Standard Product Plating:

Mate Zone:	30µIN Minimum Gold over 50µIN Minimum Nickel
Tail Zone:	$30\mu IN$ to $60\mu IN$ Matte Tin over $50\mu IN$ Minimum Nickel
Overall:	50µIN Minimum Nickel

2.3 SAFETY AGENCY APPROVALS

UL File Number: E29179

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

Refer to the appropriate sales drawings and other sections of this specification for the necessary referenced documents and specifications.

3.1 MOLEX DOCUMENTS

AS-171320-990	IMPEL Routing Guide
AS-171500-990	IMPEL Ortho Routing Guide

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3.2 COMMERCIAL STANDARDS

EIA-364 GR-1217-CORE

Electrical Connector Test Procedure Generic Requirements for Separable Electrical Connectors used In Telecommunications Hardware

4.0 RATINGS

4.1 CURRENT AND TEMPERATURE RATING

Agency Voltage: Non-Agency Voltage: Signal Contact: Temperature:

29.9 VAC RMS/DC max 150 VAC RMS/DC max 0.75 Amp per contact -55°C to 85°C

4.2 ELECTRICAL RATINGS

Description	Value
Mating interface contact resistance change	10m Ω maximum
Compliant pin to plated through hole resistance	1mΩ maximum
Insulation resistance	1000 MegaΩ
Dielectric Withstanding Voltage (except 171740 Series)	500 VAC
Dielectric Withstanding Voltage for 171740 Series	150 VAC

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5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Contact Resistance (Low Level)	Mated,100mA max, 20mV per EIA-364-TP23	10 milliohm maximum change
2A	Insulation Resistance	Unmated, 500VDC per EIA-364-TP21	1000 megaohms minimum
2B	Insulation Resistance	Mated State, 500VDC per EIA-364-TP21	1000 megaohms minimum
3A	Dielectric Withstanding Voltage	Unmated, 500VAC per EIA-364-TP20	No breakdown or flashover
3B	Dielectric Withstanding Voltage	Mated State, 500VAC per EIA-364-TP20	No breakdown or flashover
4	Signal Continuity	Mated per EIA-364-TP87	No interrupts greater than 10 nanoseconds
5	Compliant Pin Interface Resistance	Contact inserted into PCB per EIA-364-TP23	1 milliohm Maximum

5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
6	Durability	200 Cycles minimum, mated and unmated per EIA-364-TP09	10 milliohm max change in LLCR
7	Vibration	Mated, 10-500Hz, 10g's, 8 hr, 3 axis per EIA-364-TP28 with 10 ns event detection	10 milliohm max change in LLCR, zero events detected
8	Mechanical Shock	Mated, 30g half-sine,11ms, 3 axis per EIA-364-TP27 With 10 ns event detection	10 milliohm max change in LLCR, zero events detected
9	Mating Force Per Pin	Mate daughtercard and backplane assembly per EIA-364-TP13	60g max per signal pin 80g max per shield
10	Unmating Force Per Pin	Unmate daughtercard and backplane assembly per EIA-364-TP13	15g min per signal pin 15g min per shield

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5.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
11	Thermal Shock	Mated, 5 cycles from -55°C to 85°C per EIA-364-TP32	10 milliohm max change in LLCR
12	Temperature Life	Mated, 85°C for 1000 hours min per EIA-364-TP17	10 milliohm max change in LLCR
13	Humidity Cycling	Relative humidity 80 to 100% for 500 hrs per EIA-364-TP31	10 milliohm max change in LLCR
14	Dust	Unmated per EIA-364-TP91	10 milliohm max change in LLCR
15	Mixed Flowing Gas	10 days unmated 10 days mated per EIA-364-TP65 (Class IIA)	10 milliohm max change in LLCR

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PRODUCT SPECIFICATION

5.4 COMPLIANT PIN PERFORMANCE

5.4.1 Insertion Force for Various Plating Types

COMPONENT	MAX
IMPEL Backplane Pin	4 lbs
IMPEL Daughtercard Pin	4 lbs

Note: These max values are intended for press sizing only. Typical peak values are less than 4 lbs per pin. The peak force value will occur prior to the final seating of the connector. Plating surface finish and PCB materials will impact actual values.

5.4.2 Retention Force for Various Plating Types

COMPONENT	MIN		
IMPEL Backplane Pin	0.4 lb		
IMPEL Daughtercard Pin	0.4 lb		

Note: Chart reflects minimum expected values for retention forces when tested in plated through holes drilled and plated as described in Section 5.4.3. Plating surface finish and PCB materials will impact actual values.

Radial hole deformation: 1.5 mils max

Axial hole deformation: 1.0 mil max

5.4.3 Printed Circuit Board Specifications

Refer to the appropriate Sales Drawing for the recommended pcb thickness. Refer to routing guide AS-171320-990 for the detailed plated hole requirements.

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PRODUCT SPECIFICATION

5.4.4 Torque Specification for Mounting Screws

PRODUCT TYPE	SCREW TYPE	BOARD THICKNESS	RECOMMENDED TORQUE **	
BACKPLANE HEADERS	2-56 Machine Screw	6.5mm MAX	2.0 in-lbs	
DAUGHTERCARD RECEPTACLES 2-32 Self-Tapping Screw 2P		1.6mm to 2.4mm	1.0 in-lbs	
DAUGHTERCARD RECEPTACLES 3P THRU 6P	2-32 Self-Tapping Screw	4.4mm MAX	2.0 in-lbs	
Ortho Direct RAM	2-32 Self-Tapping Screw 9.50mm Length	4.4mm MAX	2.0 in-lbs	
RECEPTACLES 6P	2-32 Self-Tapping Screw 11.00mm Length	5.5mm MAX	2.0 in-lbs	

** Note: The thread forming screws used for the daughtercard guidance modules will require varying torque to seat the screw dependent upon the screw engagement in the module. The screw length and the pcb thickness will both impact the screw engagement into the module. It is recommended that the torque applied be the minimum necessary to fully seat the screw for the specific application. For applications in which the board thickness exceeds the listed recommendations, testing should be conducted to confirm that 1.0 in-lbs of torque can successfully be applied.

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PRODUCT SPECIFICATION

6.0 TES1

TEST SEQUENCE



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